ESE370: Circuit-Level Modeling, Design, and Optimization for Digital Systems

Lec 6: September 17, 2021 MOS Model



You are Here: Transistor Edition

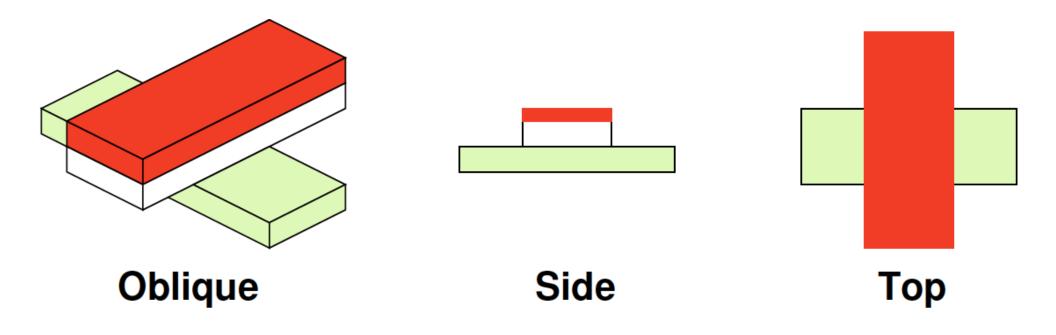
- □ Previously: simple models (0th and 1st order)
 - Comfortable with basic functions and circuits
- □ This lecture and next week(4 lectures)
 - Detailed semiconductor discussion
 - MOSFET phenomenology
 - Don't Blink!
- **Rest** of term
 - Implications of the MOS device



- MOS Structure
- Basic Fabrication
- Semiconductor Physics
 - Metals, insulators
 - Silicon lattice
 - Band gaps
 - Doping
 - Field Effects

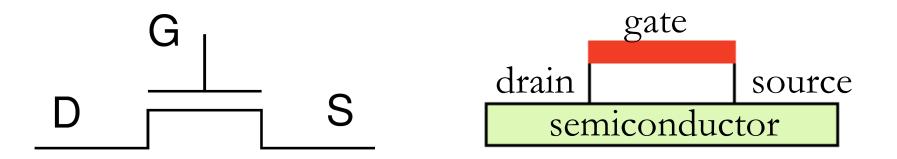


Metal Oxide Semiconductor



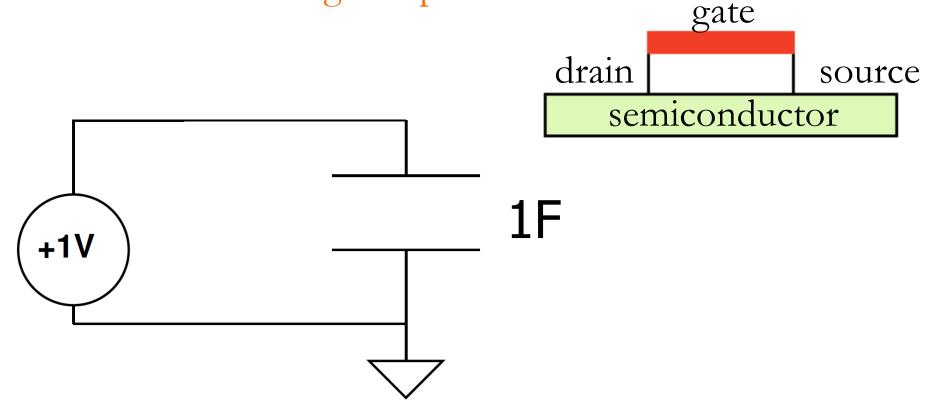


- □ Metal gate
- Oxide insulator separating gate from semiconductor
 - Ideally: no conduction from gate to semiconductor
- □ Semiconductor between source and drain
- See why gate input is capacitive?



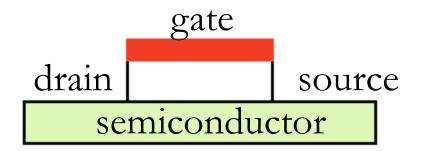


- Charge distribution and field?
- □ How much charge on plates?





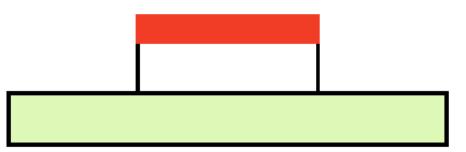
- □ Semiconductor can behave as metal or insulator
- □ Voltage on gate induces an electrical field
- Induced field attracts (repels) charge in semiconductor to form a channel
 - Semiconductor can be switched between conducting and not conducting
 - Hence "Field-Effect" Transistor







- \square Contacts: Conductors \rightarrow metallic
 - Connect to metal wires that connect transistors



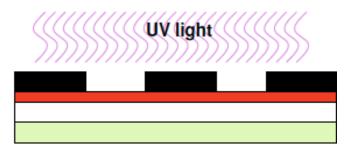


Fabrication

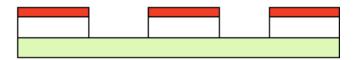
- □ Start with Silicon wafer
- Dope silicon
- □ Grow Oxide (SiO₂)
- Deposit Metal
- Photoresist mask and etch to define where features go

https://youtu.be/35jWSQXku74?t=119 Time Code: 2:00-4:30 photoresist metal SiO₂ Doped Si

Doped Si





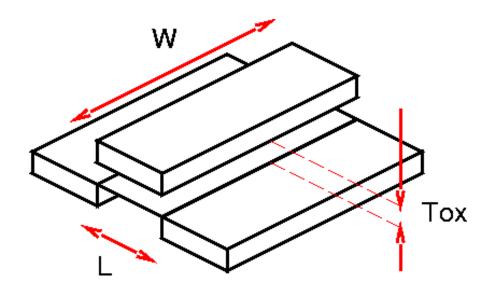




- □ Channel Length (L)
- □ Channel Width (W)
- Oxide Thickness (T_{ox})



- Process named by minimum length
 - 22nm → L=22nm



Semiconductor Physics





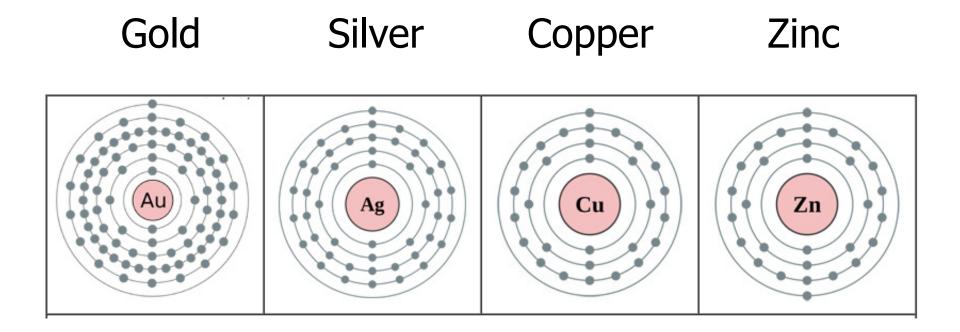
- □ Metal conducts
- Insulator does not conduct
- □ Semiconductor can act as either

Why does metal conduct? (preclass 2)

Group → ↓Period	• 1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
1	1 H																	2 He
2	3 Li	4 Be											5 B	6 C	7 N	8 0	9 F	10 Ne
3	11 Na	12 Mg											13 Al	14 Si	15 P	16 S	17 Cl	18 Ar
4	19 K	20 Ca	21 Sc	22 Ti	23 V	24 Cr	25 Mn	26 Fe	27 Co	28 Ni	29 Cu	30 Zn	31 Ga	32 Ge	33 As	34 Se	35 Br	36 Kr
5	37 Rb	38 Sr	39 Y	40 Zr	41 Nb	42 Mo	43 Tc	44 Ru	45 Rh	46 Fd	47 Ag	49 Cd	49 In	50 Sn	51 Sb	52 Te	53 	54 Xe
6	55 Cs	56 Ba		72 Hf	73 Ta	74 W	75 Re	76 Os	77 Ir	78 Pt	79 Au	80 Hg	81 Tl	82 Pb	83 Bi	84 Po	85 At	86 Rn
7	87 Fr	88 Ra		104 Rf	105 Db	106 Sg	107 Bh	108 Hs	109 Mt	110 Ds	111 Ba	112 UUb	113 Uut	114 Uuq	115 Uup	116 Uuh	117 Uus	118 Uuo
	Lanthanides				58 Ce	59 Pr	60 Nd	61 Pm	62 Sm	63 Eu	64 Gd	65 Tb	66 Dy	67 Ho	68 Er	69 Tm	70 Yb	71 Lu
	Actinides				90 Th	91 Pa	92 U	93 Np	94 Pu	95 Am	96 Cm	97 Bk	98 Cf	99 Es	100 Fm	101 Md	102 No	103 Lr

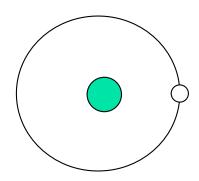
http://chemistry.about.com/od/imagesclipartstructures/ig/Science-Pictures/Periodic-Table-of-the-Elements.htm





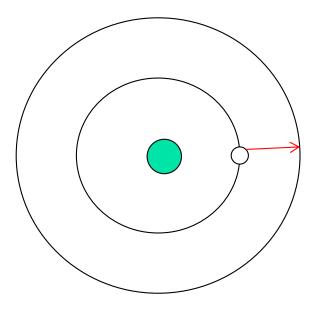


- Electrons move
- Must be able to "remove" electron from atom or molecule



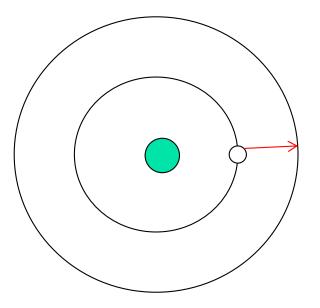


- Quantized Energy Levels (bands)
 - Valence and Conduction Bands
- □ Must have enough energy to change level (state)



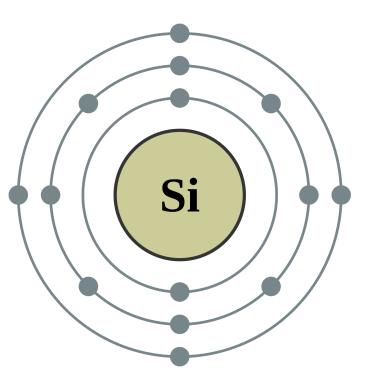


- Except at absolute 0
 - There is always free energy
 - Causes electrons to hop around
 -when there is enough energy to change states
 - Energy gap between states determines energy required



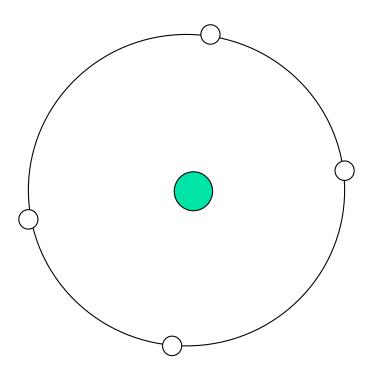


□ How many valence electrons?



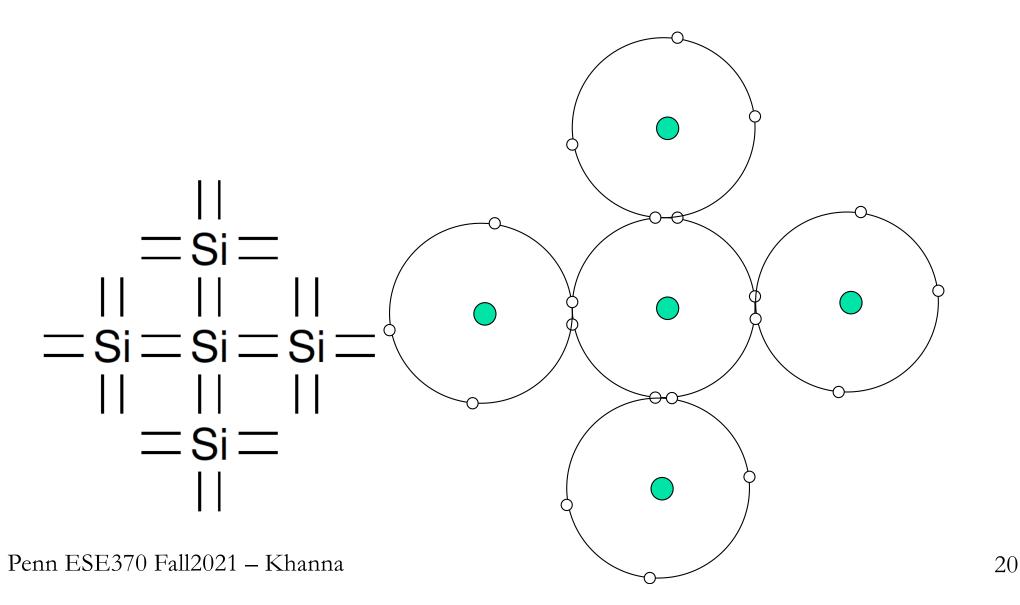


- □ 4 valence electrons
 - Inner shells filled
 - Only outer shells contribute to chemical interactions





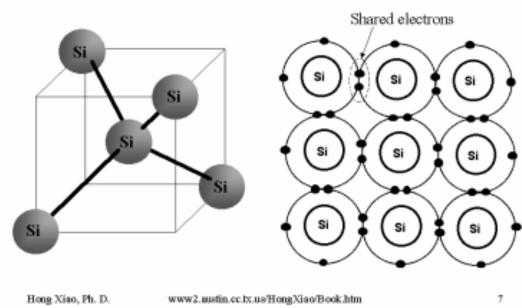
• Can form covalent bonds with 4 other silicon atoms

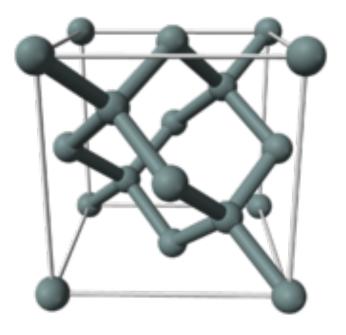




• Forms into crystal lattice

Crystal Structure of Single Crystal Silicon





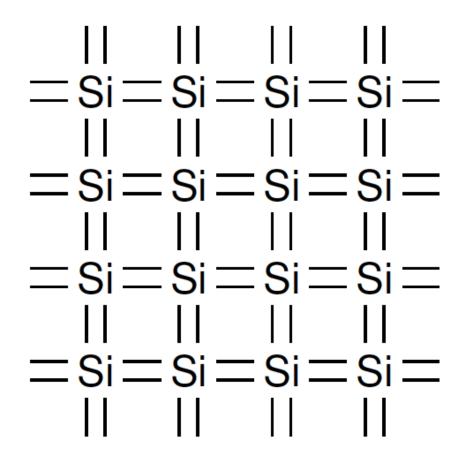


1 impurity atom per 10 billion silicon atoms



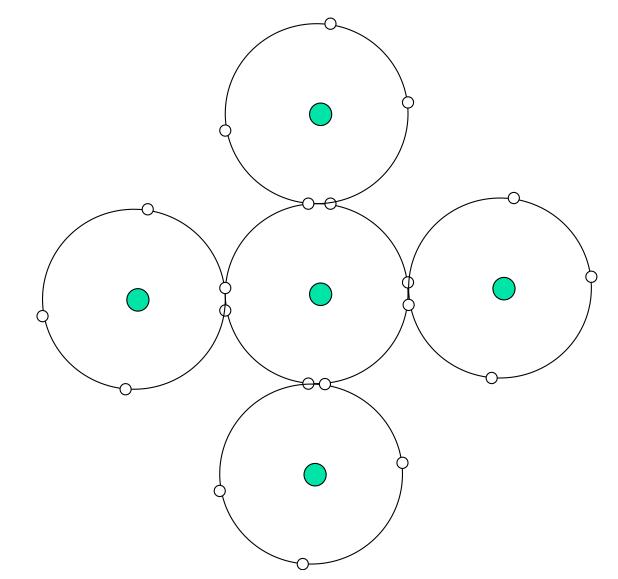


• Cartoon two-dimensional view



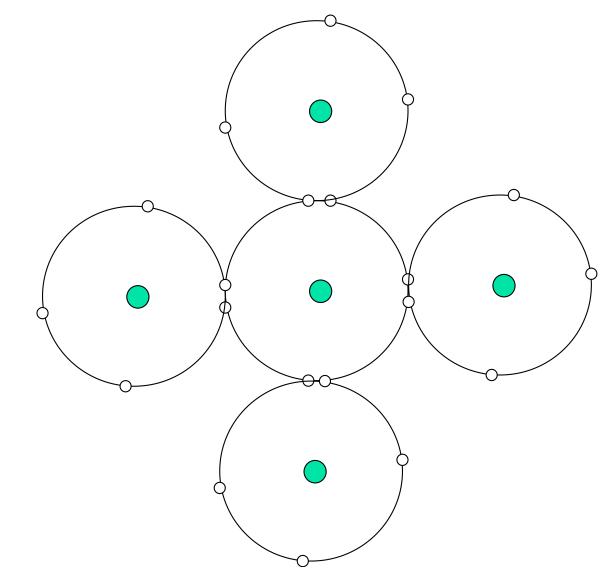


□ What happens to outer shell in Silicon lattice?





□ What does this say about energy to move electron?





Energy

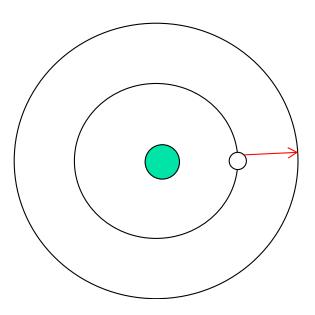
Valance Band – all states filled



Conduction Band- all states empty

Energy

Valance Band – all states filled

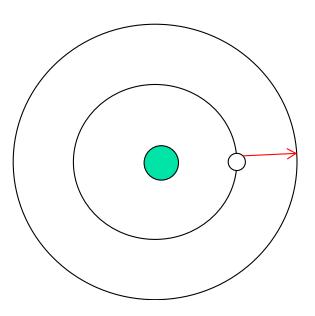




Conduction Band- all states empty

Band Gap

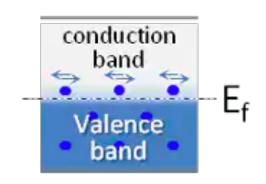
Valance Band – all states filled

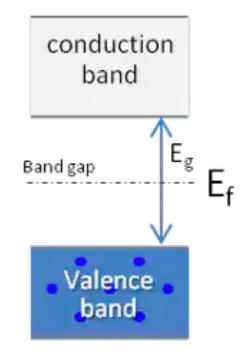


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Energy

Band Gap and Conduction

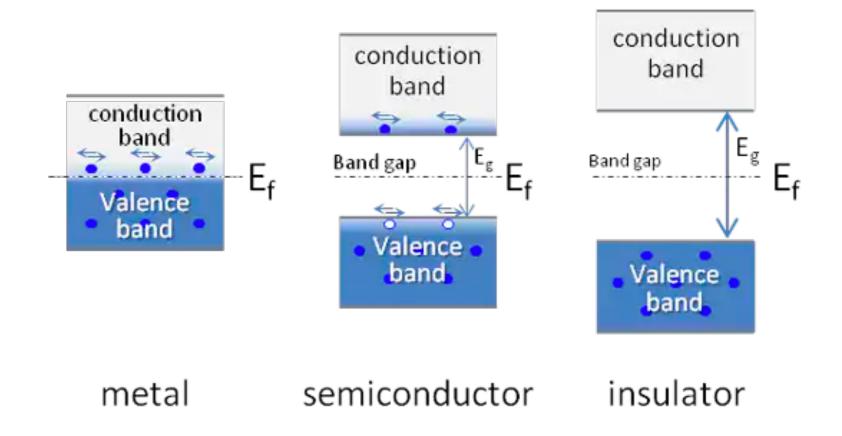


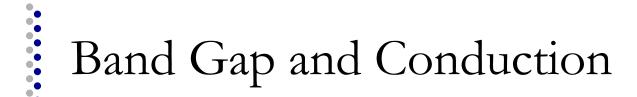


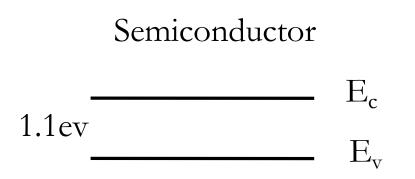
metal

insulator

Band Gap and Conduction





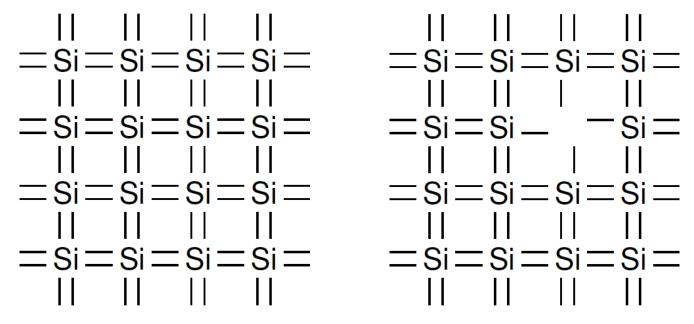


 $1eV = 160 \text{ zeptojoules } (10^{-21} \text{ J})$



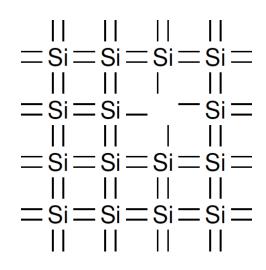
Add impurities to Silicon Lattice

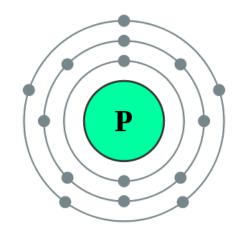
• Replace a Si atom at a lattice site with another





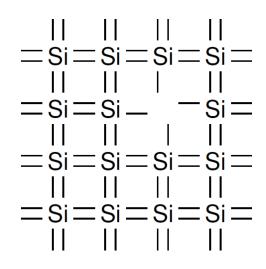
- Add impurities to Silicon Lattice
 - Replace a Si atom at a lattice site with another
- Add a Group 15 element
 - E.g. P (Phosphorus)
 - How many valence electrons?

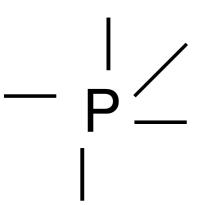




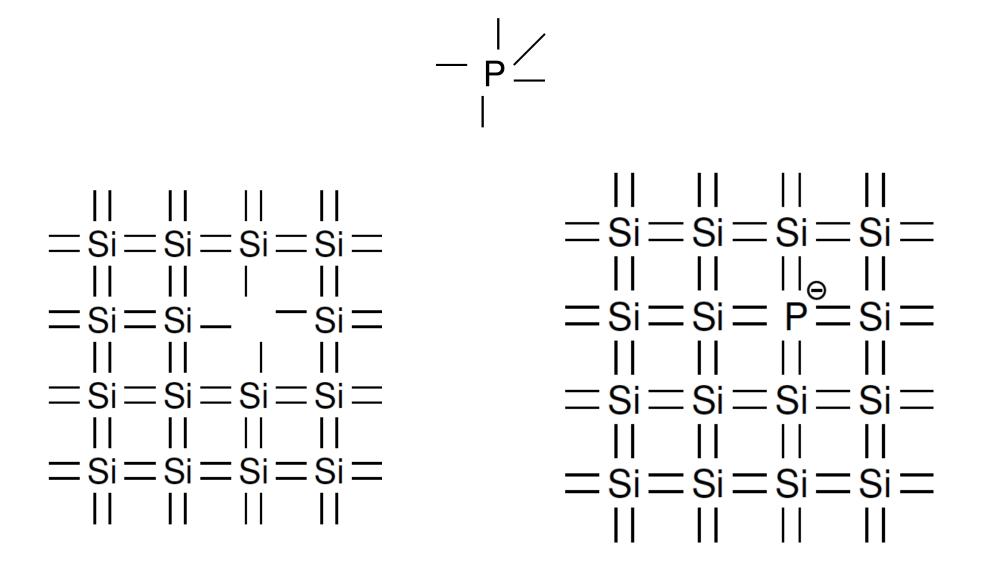


- Add impurities to Silicon Lattice
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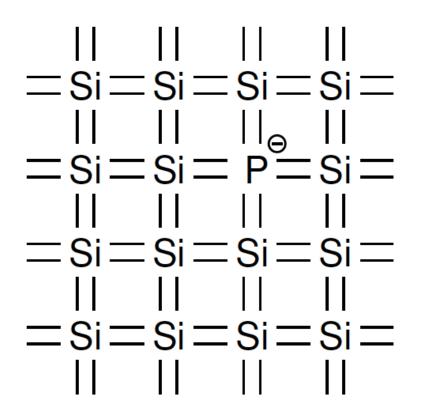








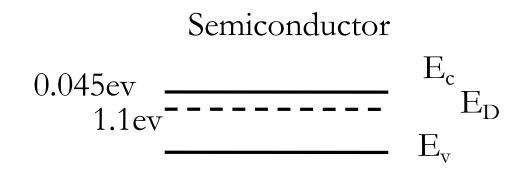
- End up with extra electrons
 - Donor electrons
- Not tightly bound to atom
 - Low energy to displace
 - Easy for these electrons to move





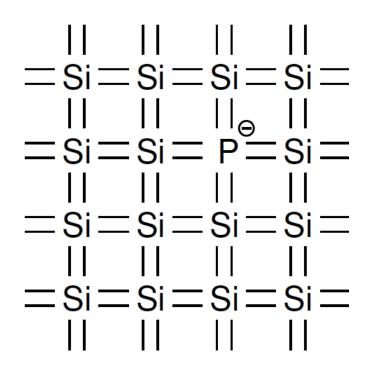
Addition of donor electrons makes more metallic

Easier to conduct



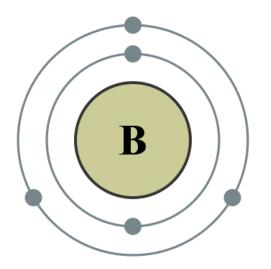


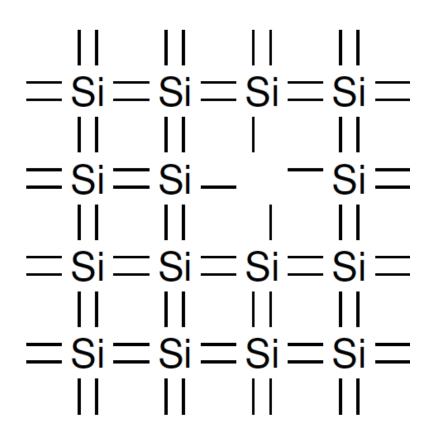
- Donor electron is localized
 - Won't go far if no low energy states nearby
- Increasing doping concentration
 - Ratio of P atoms to Si atoms
 - Decreases energy to conduct





- What happens if we replace Si atoms with group 13 atom instead?
 - E.g. B (Boron)
 - Valance band electrons?



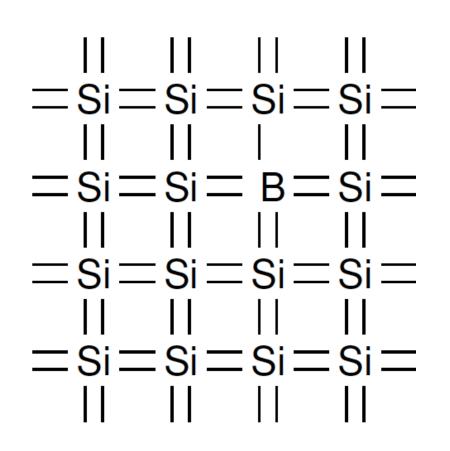


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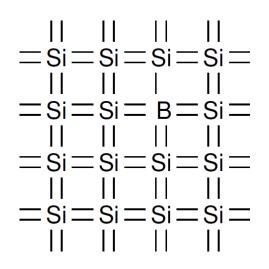
- What happens if we replace Si atoms with group 13 atom instead?
 - E.g. B (Boron)
 - Valance band electrons?

B'





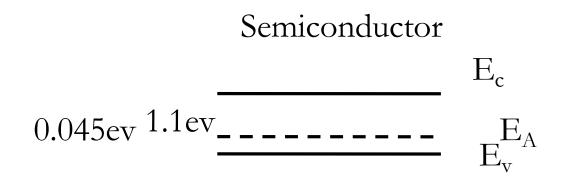
- □ End up with electron vacancies -- Holes
 - Acceptor electron sites
- Easy for electrons to shift into these sites
 - Low energy to displace
 - Easy for the electrons to move
 - Movement of an electron best viewed as movement of hole





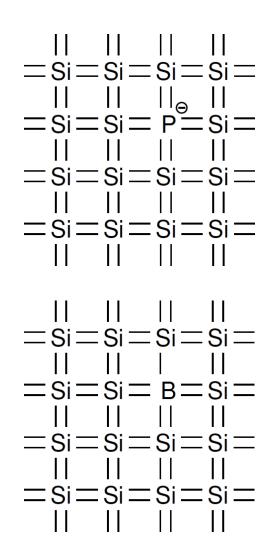
Addition of acceptor sites makes more metallic

Easier to conduct



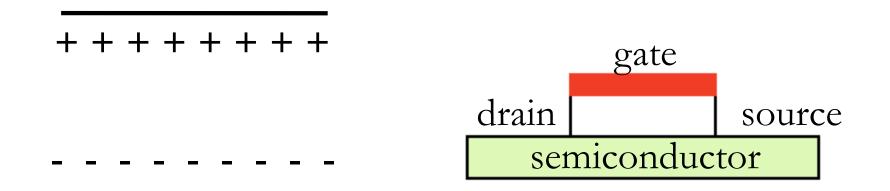


- Donor doping
 - Excess electrons
 - Negative or N-type material
 - NFET
- Acceptor doping
 - Excess holes
 - Positive or P-type material
 - PFET

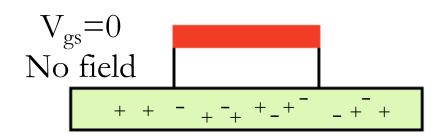




Remember capacitor charge





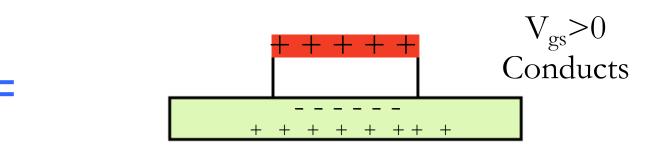










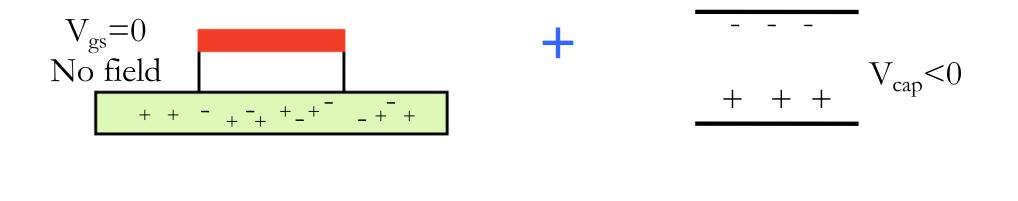


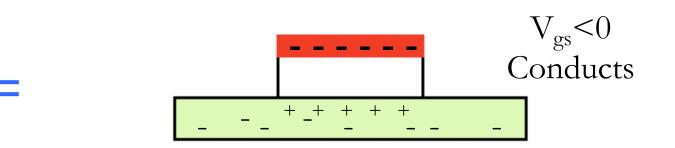
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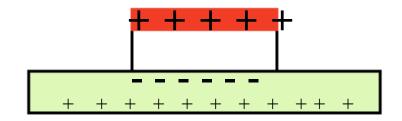


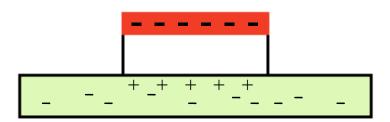


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- Charge on capacitor
 - Attract or repel charges to form channel
 - NMOS: Positive field on p-type substrate
 - Attracts electrons to surface to form conducting channel
 - PMOS: Negative fiend on n-type substrate
 - Attracts holes to surface to form conducting channel





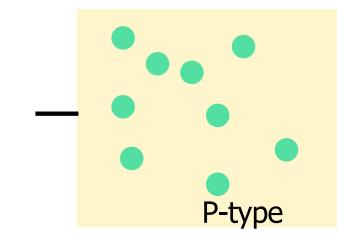
PN Junction

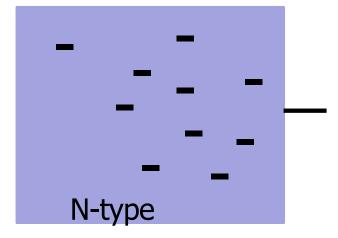




=hole

– =electron



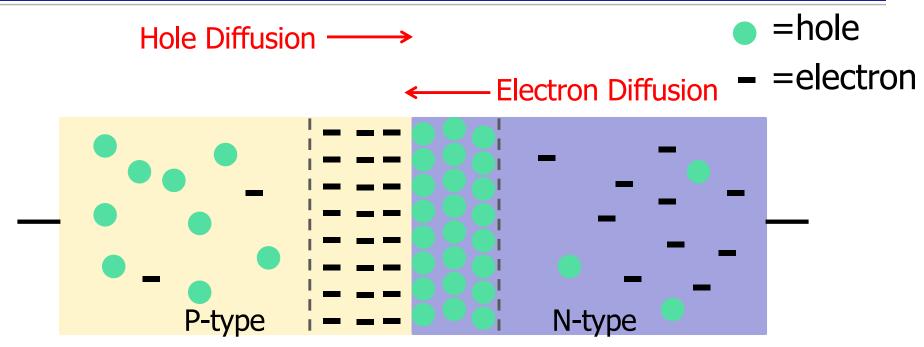


Excess holes

Excess electrons

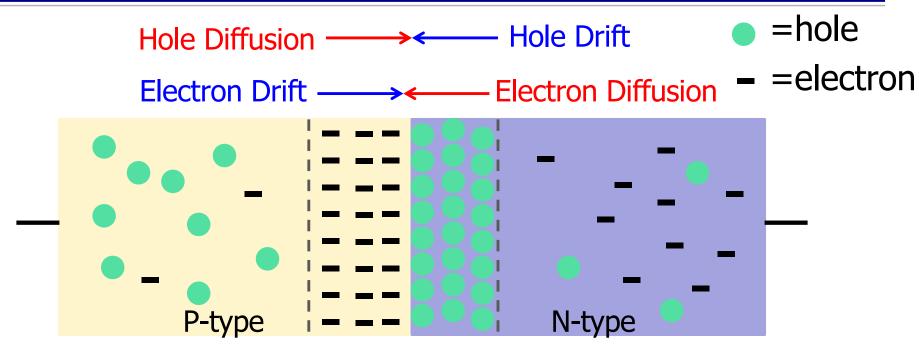
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- PN junction causes a depletion region to form
 - Electrons diffuse from N-type to P-type
 - Holes diffuse from P-type to N-type
 - Diffusion current caused by diffusion of carriers





- PN junction causes a depletion region to form
 - Electrons diffuse from N-type to P-type
 - Holes diffuse from P-type to N-type
 - Diffusion current caused by diffusion of carriers
- Equilibrium achieved when V_{bi}, built-in potential, is formed across the depletion region
 - Drift current cause by E-field due to V_{bi} to counteract diffusion current

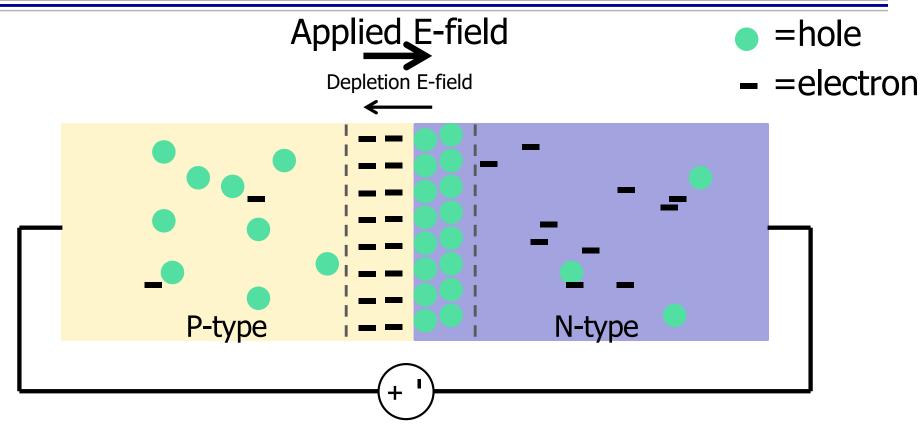
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Drift/Diffusion Currents

- Diffusion current
 - Current caused by semiconductor diffusion of holes and electrons
- Drift current

• Current due to movement of holes and electrons caused by force from potential difference induced e-field

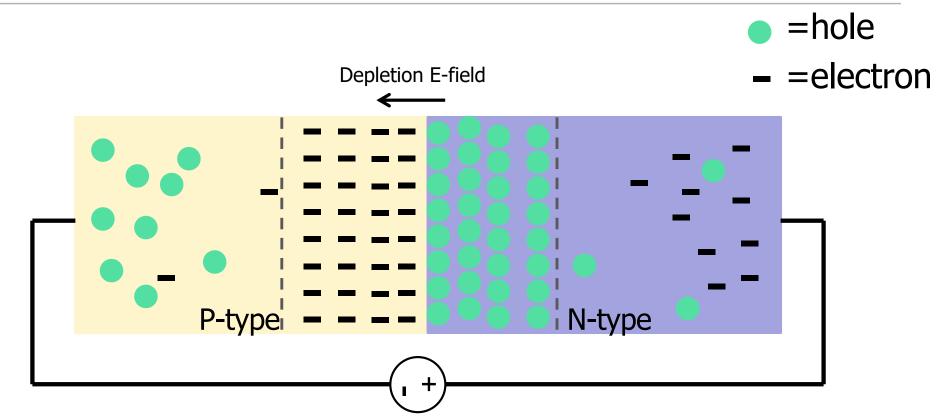
PN Junction – Forward Biasing



- Forward biasing connect positive terminal to p-type and negative terminal to n-type
 - Holes/electrons pushed towards depletion region, causing it to narrow
 - The applied voltage e-field continues to narrow the depletion region (i.e reduce the depletion e-field)
 - current flows through the device from p-type to n-type

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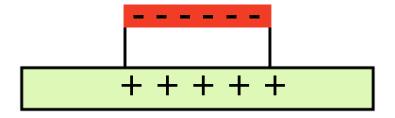




- Reverse biasing connect positive terminal to n-type and negative terminal to p-type
 - Holes/electrons attracted away from depletion region, causing it to widen
 - No current flows through the device
- If reverse bias increases past breakdown voltage, the depletion e-field ٠ increases until breakdown occurs and reverse biased current flows causing thermal damage to junction Penn ESE 370 Fall 2021 - Khanna



- Semiconductor can act like metal or insulator
- Use electric field to modulate conduction state of semiconductor





□ HW 2 due Monday

- More Fabrication Videos:
 - From sand to silicon (intel) -<u>https://www.youtube.com/watch?v=Q5paWn7bFg4</u>
 - How microchips are made -<u>https://www.youtube.com/watch?v=F2KcZGwntgg</u>